

Title (en)

Cooling assembly with direct cooling of active electronic components

Title (de)

Kühlvorrichtung mit Direktkühlung aktiver elektronischer Komponenten

Title (fr)

Ensemble de refroidissement doté d'un refroidissement direct des composants électroniques actifs

Publication

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Application

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Priority

- EP 02797492 A 20021223
- US 2647101 A 20011227
- US 2646901 A 20011227

Abstract (en)

The invention relates to a probe card assembly (300) comprising spring probe elements (305); and a package (400) coupled to the probe elements (305), wherein the package includes at least one die (430a-c) with active electronic components, the die (430a-c) electrically connected to the package by a plurality of first compliant interconnects (432a-c), wherein each of the first compliant interconnects is a structural element that is structurally distinct from each of the probe elements (305), and at least one coolant port (442, 444) that allows a coolant to enter the package (400) and directly cool the active electronic components of each die (430a-c) during a testing operation. Therein the probe elements (305) are directly connected to the package (400).

IPC 8 full level

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CPC (source: EP KR)

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Citation (applicant)

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